

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
7 August 2003 (07.08.2003)

PCT

(10) International Publication Number
WO 03/064713 A1

(51) International Patent Classification⁷: **C22C 28/00**

(21) International Application Number: PCT/US02/12821

(22) International Filing Date: 23 April 2002 (23.04.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/354,051 30 January 2002 (30.01.2002) US

(71) Applicant (*for all designated States except US*): **HONEYWELL INTERNATIONAL INC.** [US/US]; Box 2245, 101 Columbia Road, Morristown, NJ 07962 (US).

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **LALENA, John, N.** [US/US]; 17317 94th Ave., Ct. E., Puyallup, WA 98375 (US). **DEAN, Nancy, F.** [US/US]; 1827 S. Liberty Drive, Liberty Lake, WA 99019 (US). **WEISER, Martin, W.** [US/US]; 1009 N. Drury Court, Liberty Lake, WA 99019 (US).

(74) Agents: **LATWESEN, David, G.**; Wells, St. John, 601 West First Avenue, Suite 1300, Spokane, WA 99201 et al. (US).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

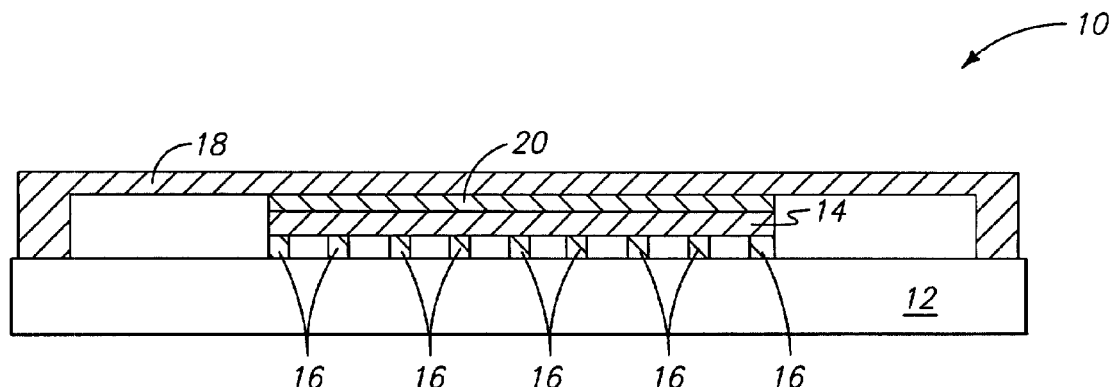
(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- with amended claims

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: THERMAL INTERFACE MATERIALS; AND COMPOSITIONS COMPRISING INDIUM AND ZINC



(57) Abstract: The invention includes a semiconductor package (10) which comprises a semiconductor substrate (14) and a heat spreader (18). A thermal interface material (20) thermally connects the substrate to the heat spreader (18). The thermal interface material (20) consists essentially of In, Zn, and one or more elements selected from the group consisting of Mg, Ca, Nb, Ta, B, Al, Ce, Ti and Zr. The invention also includes a composition consisting essentially of In and Zn. The Zn concentration within the composition is from about 0.5 weight% to about 3 weight%.



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